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(12) **United States Design Patent**
Kim et al.

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(54) **THREE DIMENSIONAL FACETED IDENTIFICATION CHIP**

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(73) Assignee: **LEXMARK INTERNATIONAL, INC.**, Lexington, KY (US)

(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **14-02**

(52) **U.S. Cl.**
USPC **D14/384**

(58) **Field of Classification Search**
USPC D14/356–358, 383–385, 420, 426, 427,
D14/432–439, 447, 453, 454, 217, 253,
D14/299, 307; D13/107, 108, 133, 146,
D13/147, 152, 154, 156, 158, 162, 162.1,
D13/168, 173, 177, 102; 235/441, 451,
235/492, 380, 439, 375; 361/679.31, 600,
361/679.01, 679.02
CPC G07C 9/00103; G07C 9/00039; G07C 9/00904; G06K 5/00; G06K 7/01
See application file for complete search history.

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Primary Examiner — Austin Murphy

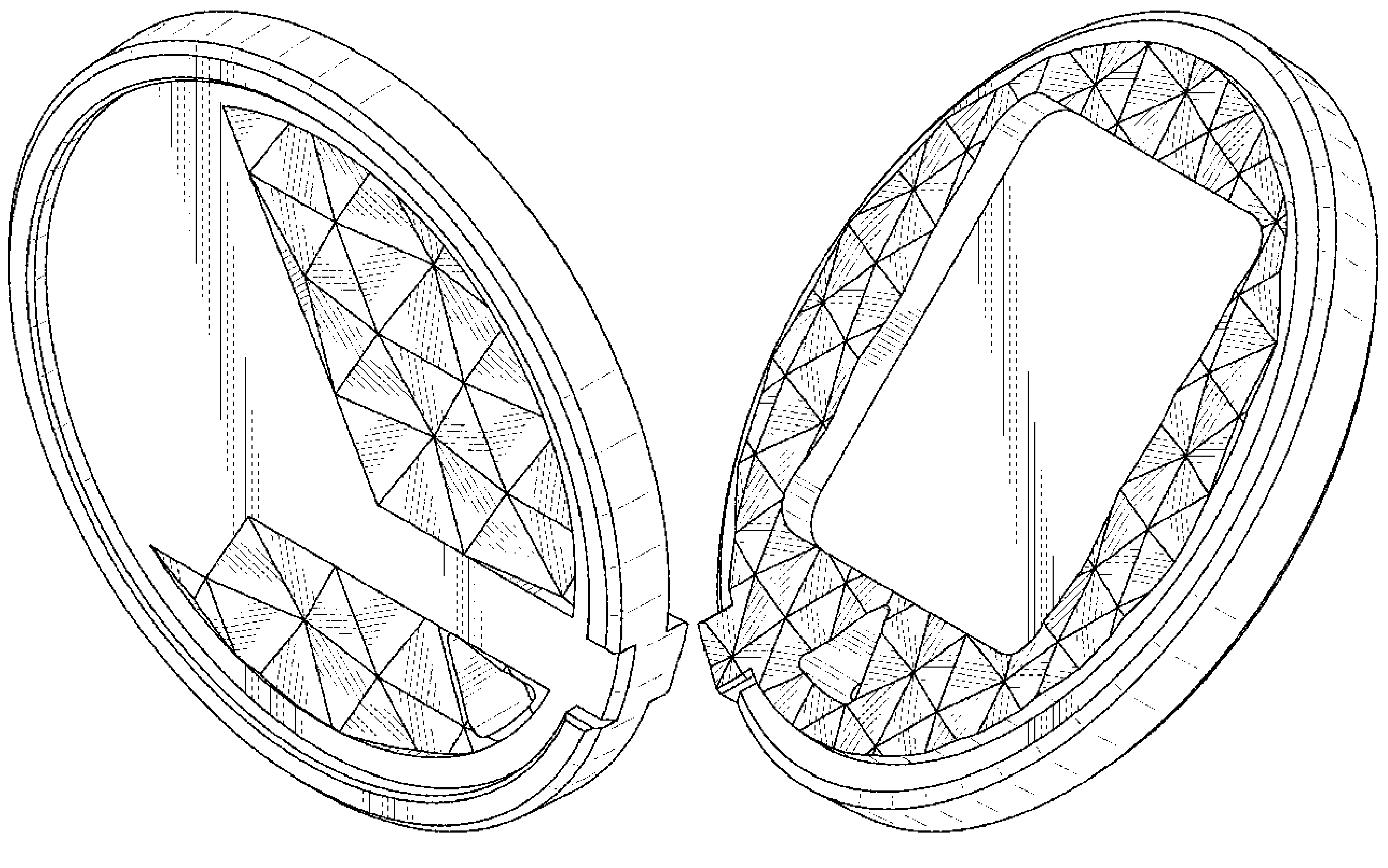
(57) **CLAIM**

The ornamental design for three dimensional faceted identification chip, as shown and described.

DESCRIPTION

FIG. **1** is a front, top, and right side perspective view of a three dimensional faceted identification chip showing our new design;
FIG. **2** is a rear, bottom, and left side perspective thereof;
FIG. **3** is front elevation thereof;
FIG. **4** is a right side elevation thereof;
FIG. **5** is a rear elevation thereof;
FIG. **6** is a left side elevation thereof;
FIG. **7** is a top plan view thereof;
FIG. **8** is a bottom plan view thereof;
FIG. **9** is a section view thereof, as identified in FIG. **3**;
FIG. **10** is a section view thereof, as identified in FIG. **3**; and,
FIG. **11** is a section view thereof, as identified in FIG. **3**.
The features shown in broken lines depict environmental subject matter only and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



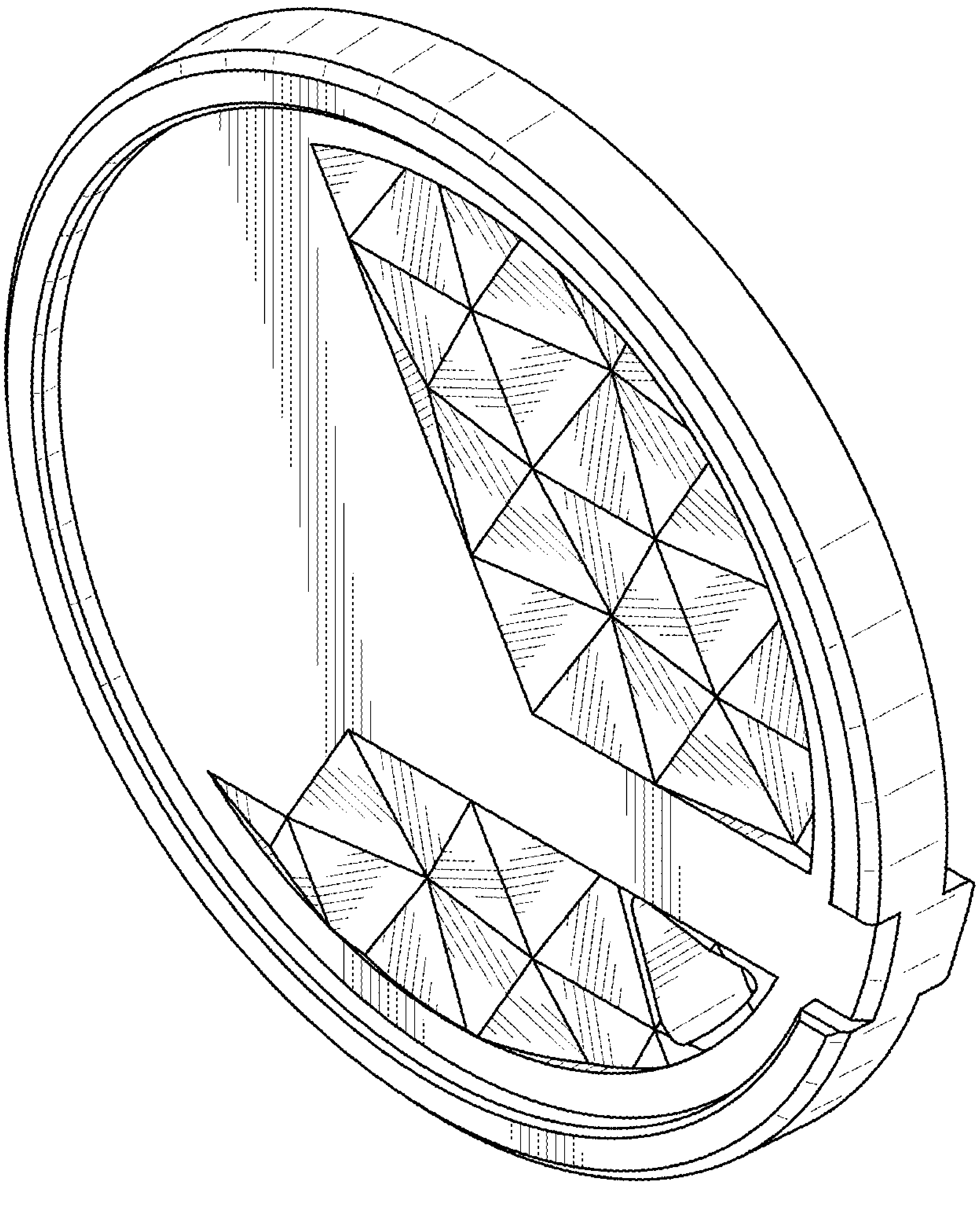


FIG. 1

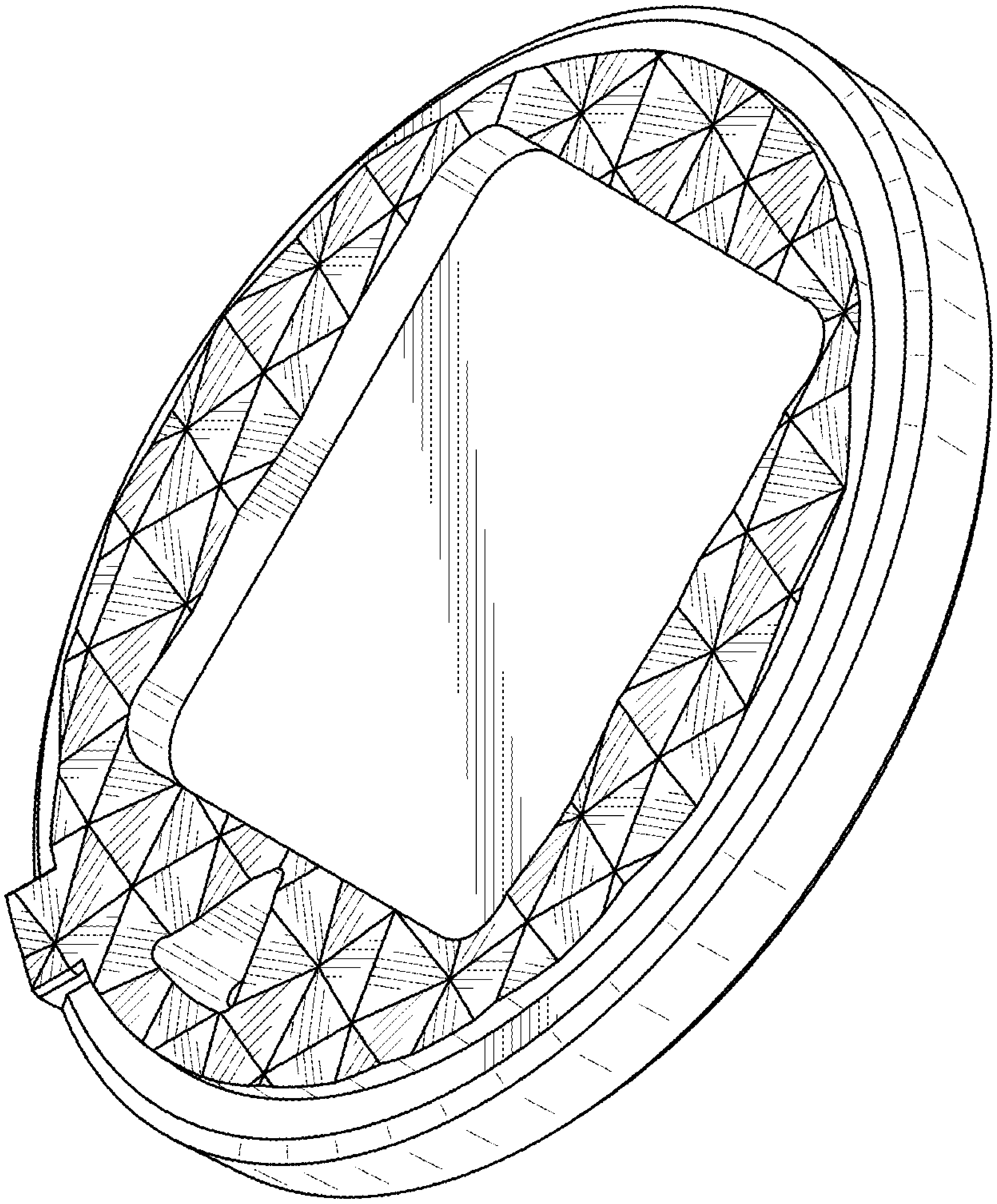


FIG. 2

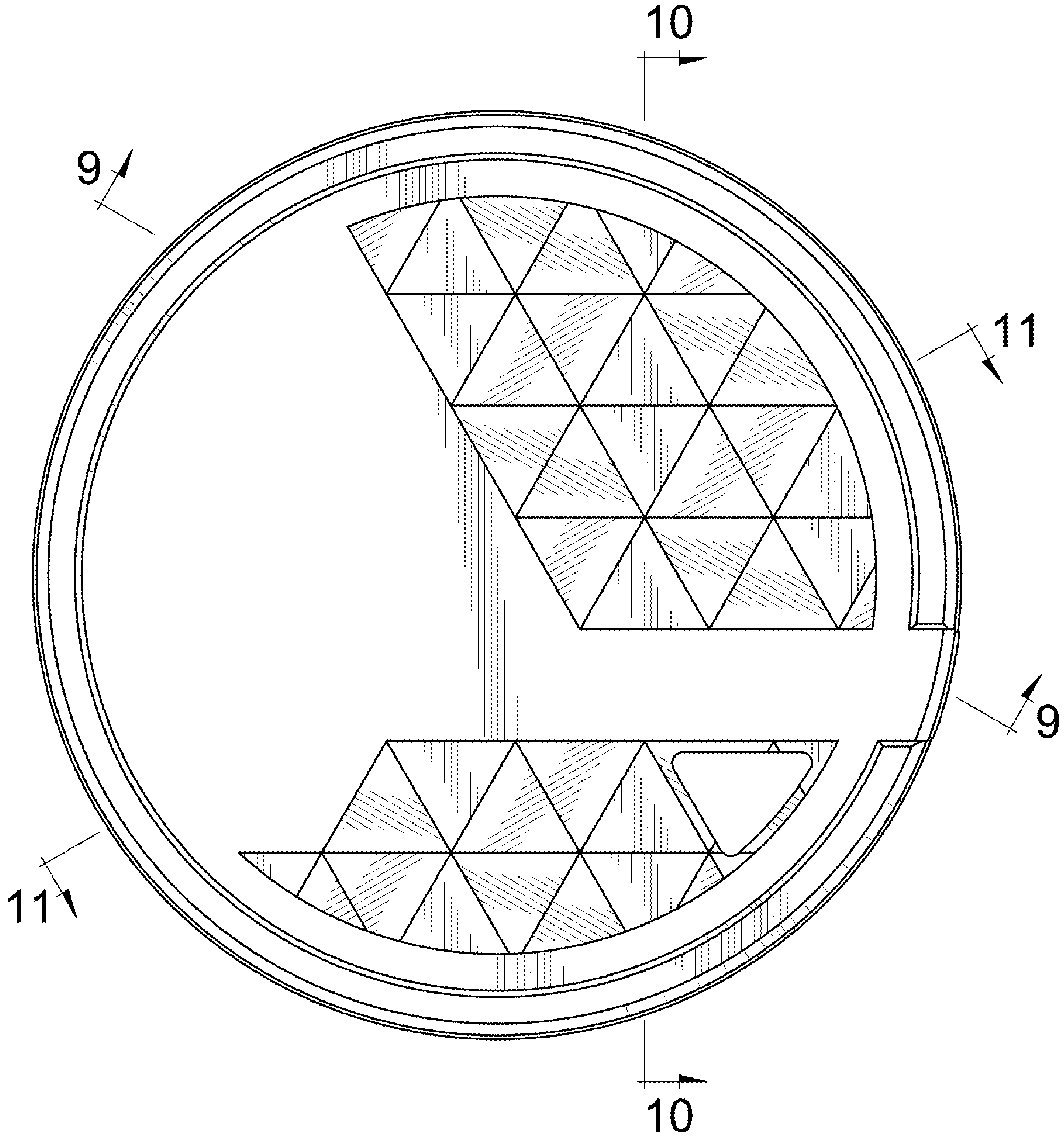


FIG. 3

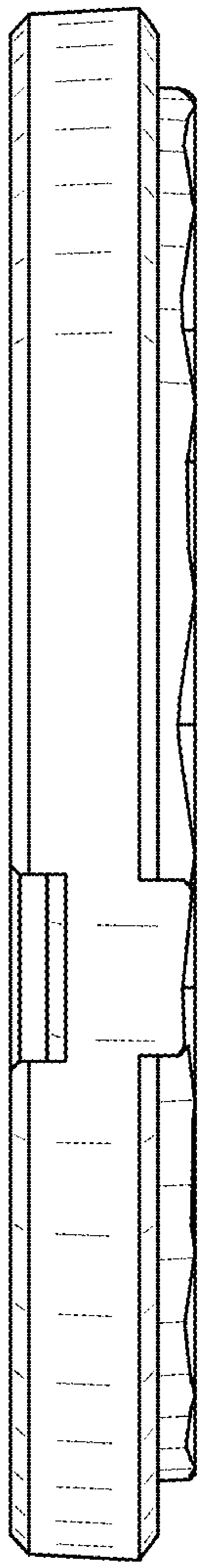


FIG. 4

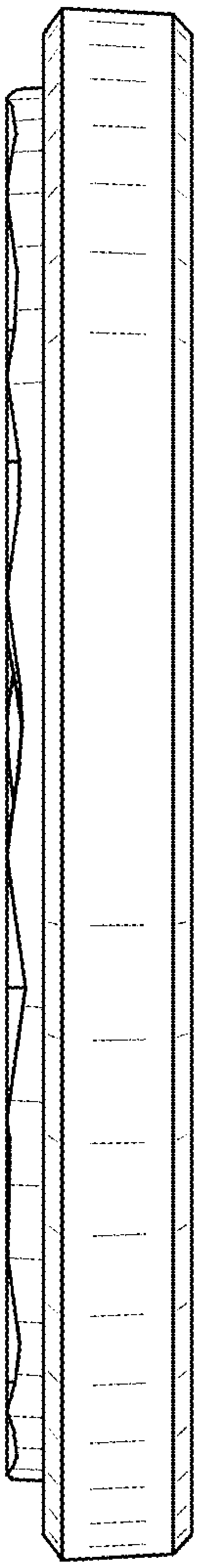


FIG. 6

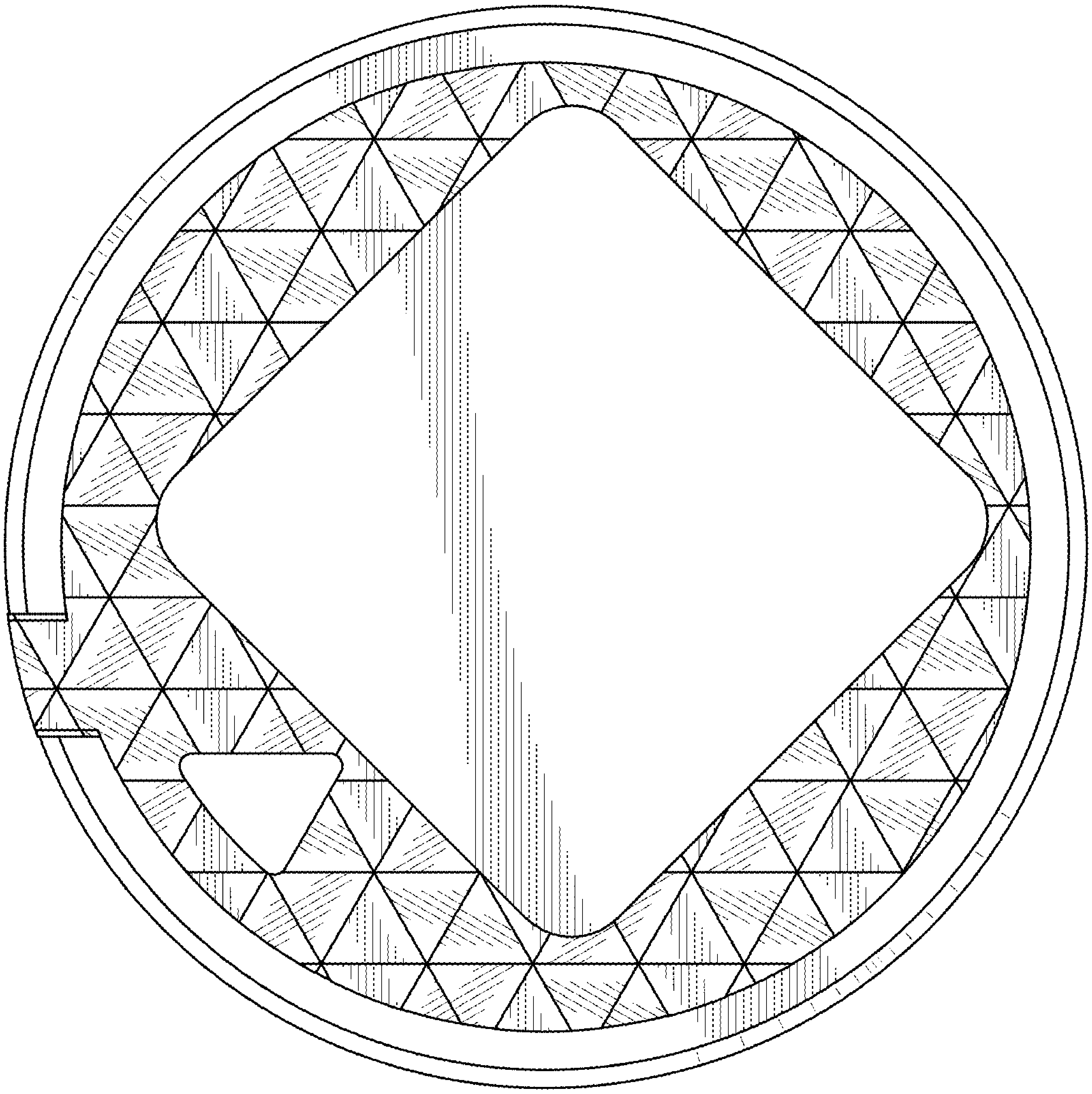


FIG. 5

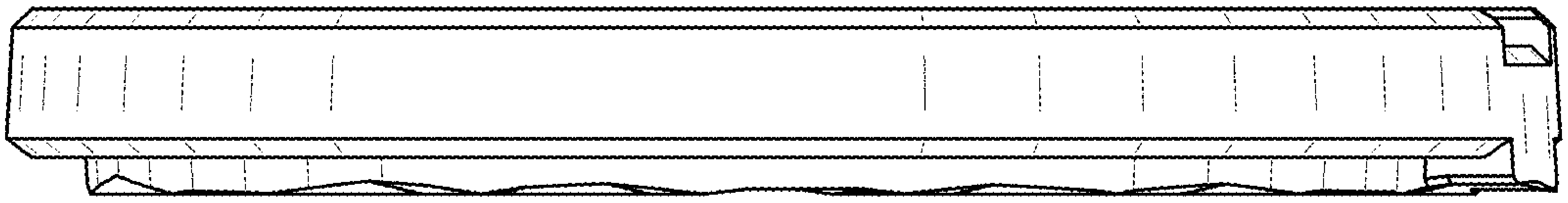


FIG. 7

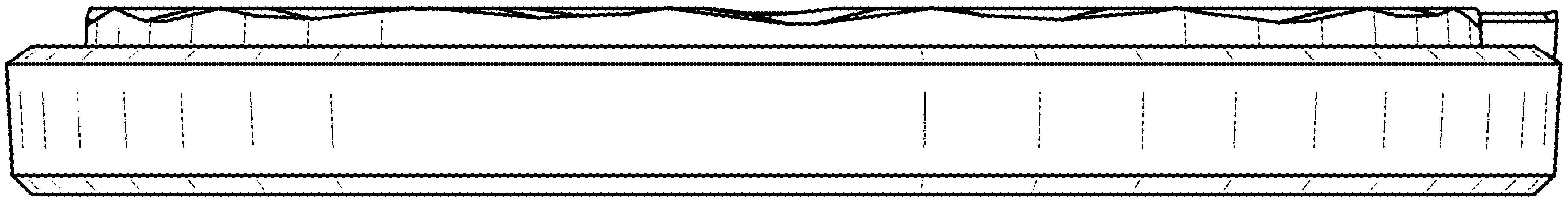


FIG. 8

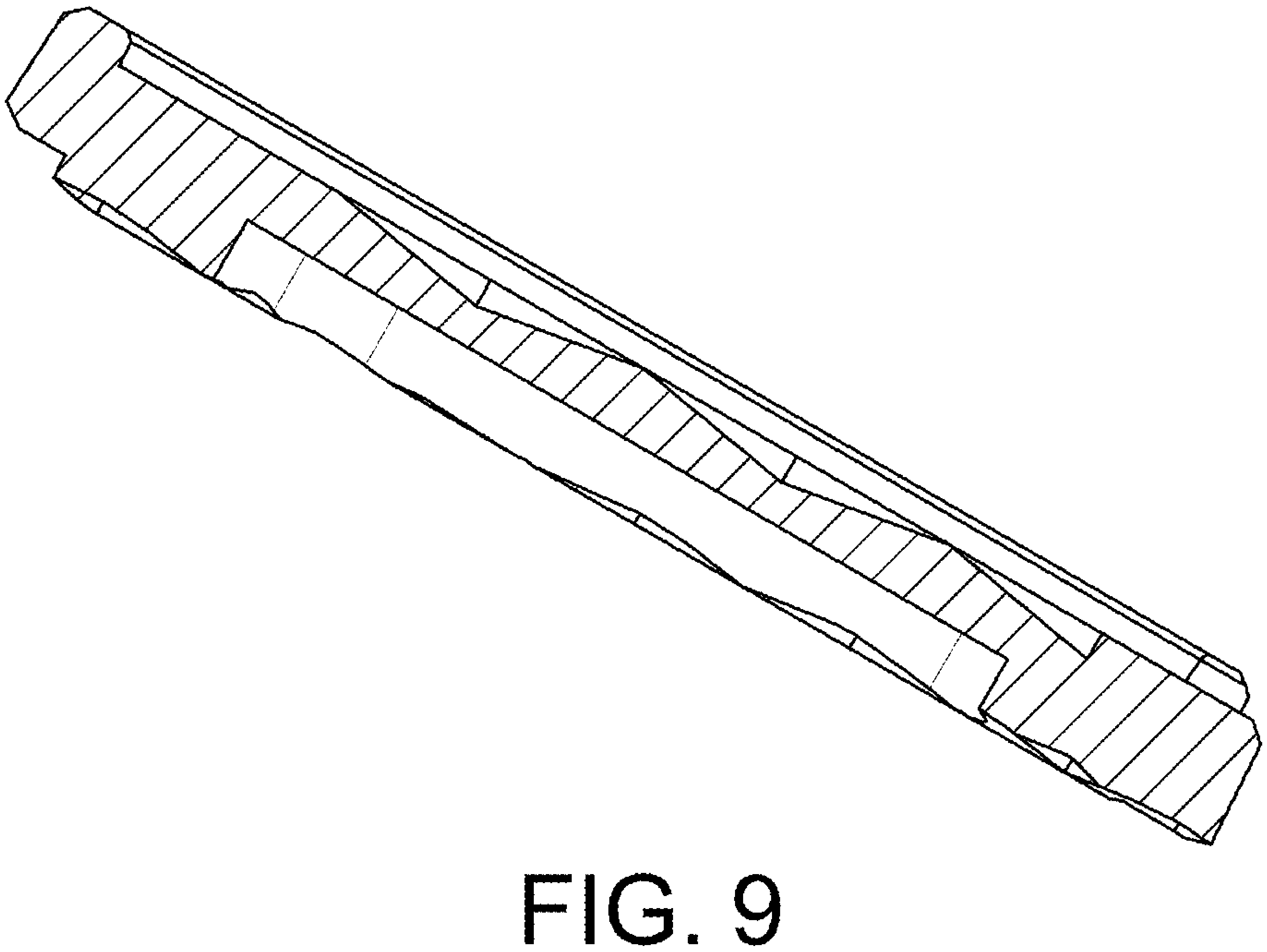


FIG. 9

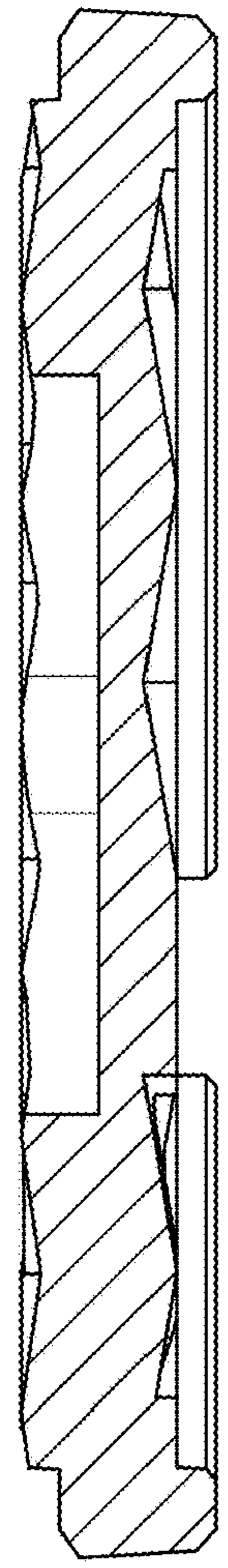


FIG. 10

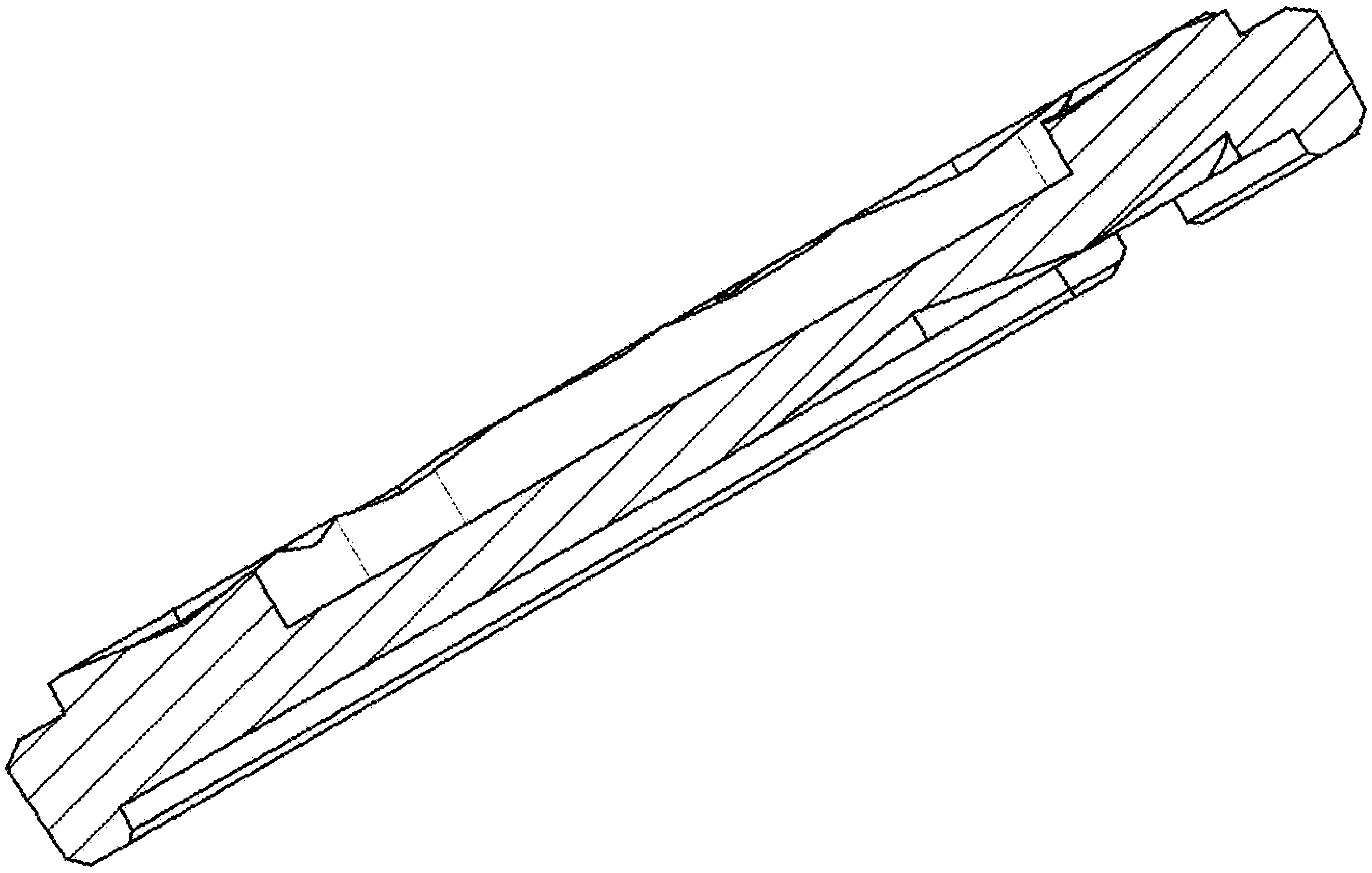


FIG. 11